

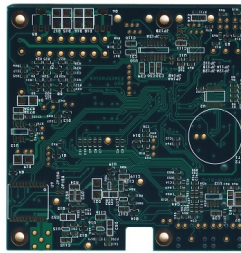
PCB - Printed Circuit Boards

Glass Fibre FR4 PCB - Process parameters

ELECSOUND®

Applications

Medical Equipment
Vehicle Device
Industrial Equipment
Security Device
Power Supply Device
Communication Device
Consumer Electronics Device
Computer Products



Process parameters

Content	Capability
Material	FR4, TG130, TG140, TG160, TG170
Surface treatment	HASL, Chemical Tin, ENIG (Immersion GOLD), OSP, IMT, Plating silver, GOLD Finger
Layers	Single-sided, double-sided, 4 layers, 6, 8, 10, 12 Layers
Maxi. board size	800mm X 508mm
Line width/space	0.1mm / 0.1mm
Board thickness	0.2mm - 4mm
Min. tolerance of Board thickness	+/- 8% - 10%
Copper foil thickness	Out Layer: 17.5um/35um/70um/105um/140um/175um Inner Layer: 17.5um/35um/70um/105um/140um
Outline Tolerance	CNC routing: +/- 0.1mm, Punching: +/- 0.1mm
V-CUT registration	+/- 0.15mm
PTH hole copper thickness	15um - 50um
Warp and twist	<= 1%
Min. registration of hole position	+/- 3mil (+/- 0.76mm)
Min. punching hole	0.8mm (Board thickness below 1.0mm)
Min. Punching Square slot	(Board thickness below 1.0mm, 1.0mm X 1.0mm)
Registration of printed circuit	+/- 0.076mm
Min. drill hole diameter	0.2mm
Min. tolerance of hole diameter	+/- 0.05mm
Thickness of surface treatment	Plating Gold: (Ni 4um - 6um, Au 0.1um - 0.5um), Immersion GOLD: (Ni 5um - 6um, Au: 0.0254um - 0.127um), Plating Silver: (Ag 5um - 8um),
V-CUT degree tolerance	+/- 5 (degree)
V-CUT Board thickness	0.6mm - 3.2mm
Min. Legend width	0.1mm
Min. Solder mask width	0.1mm
Min. Solder mask ring	0.05mm

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